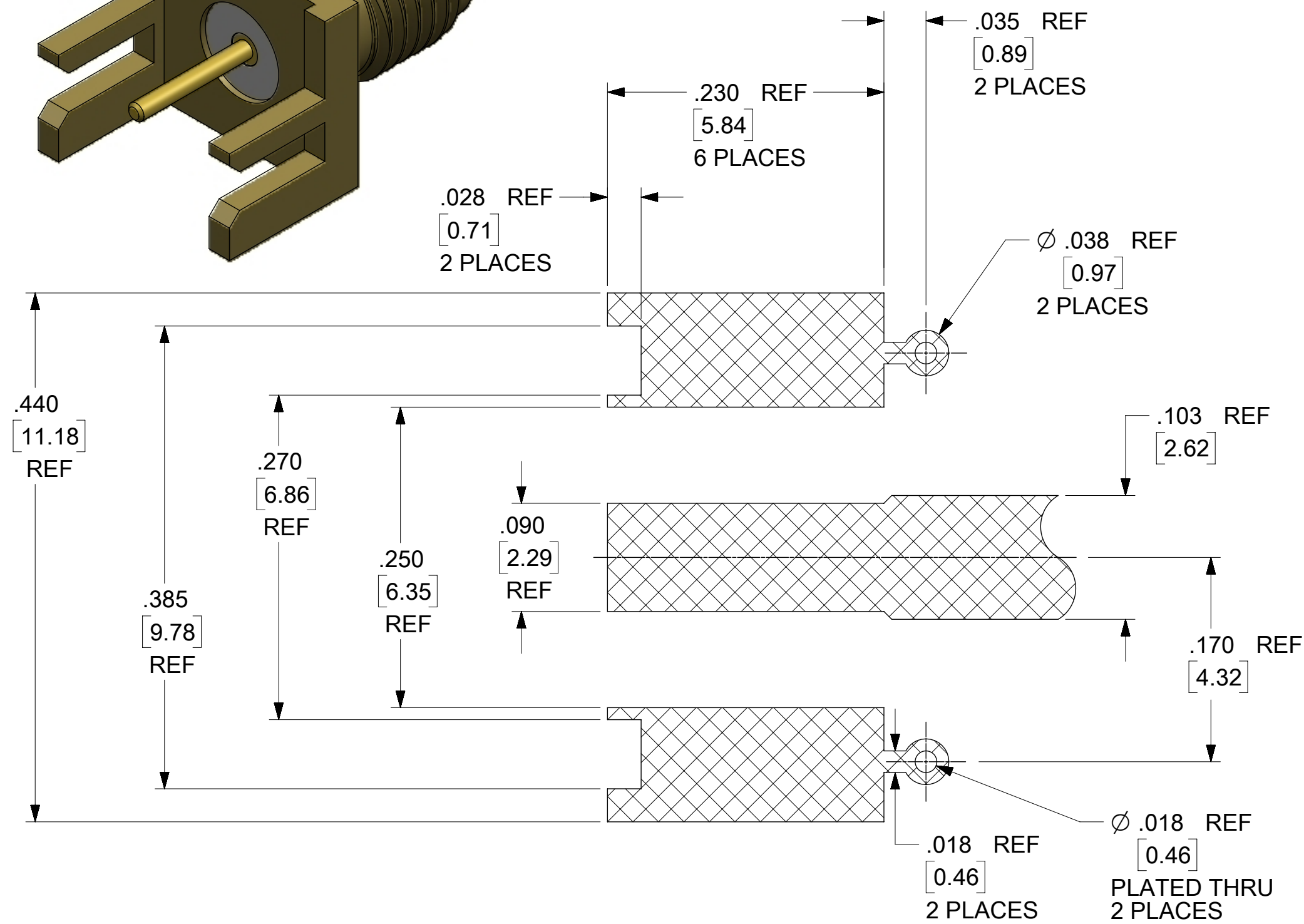
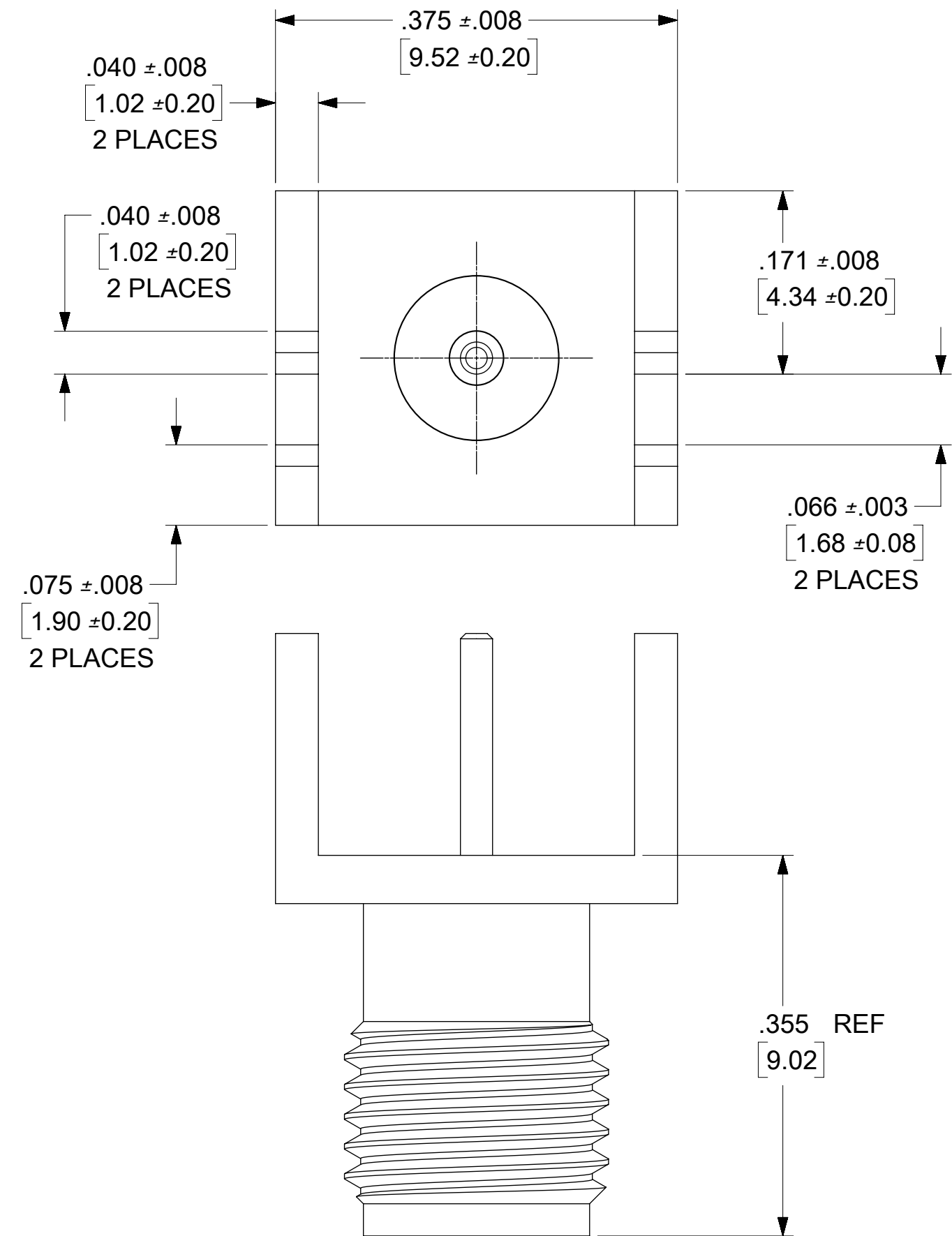
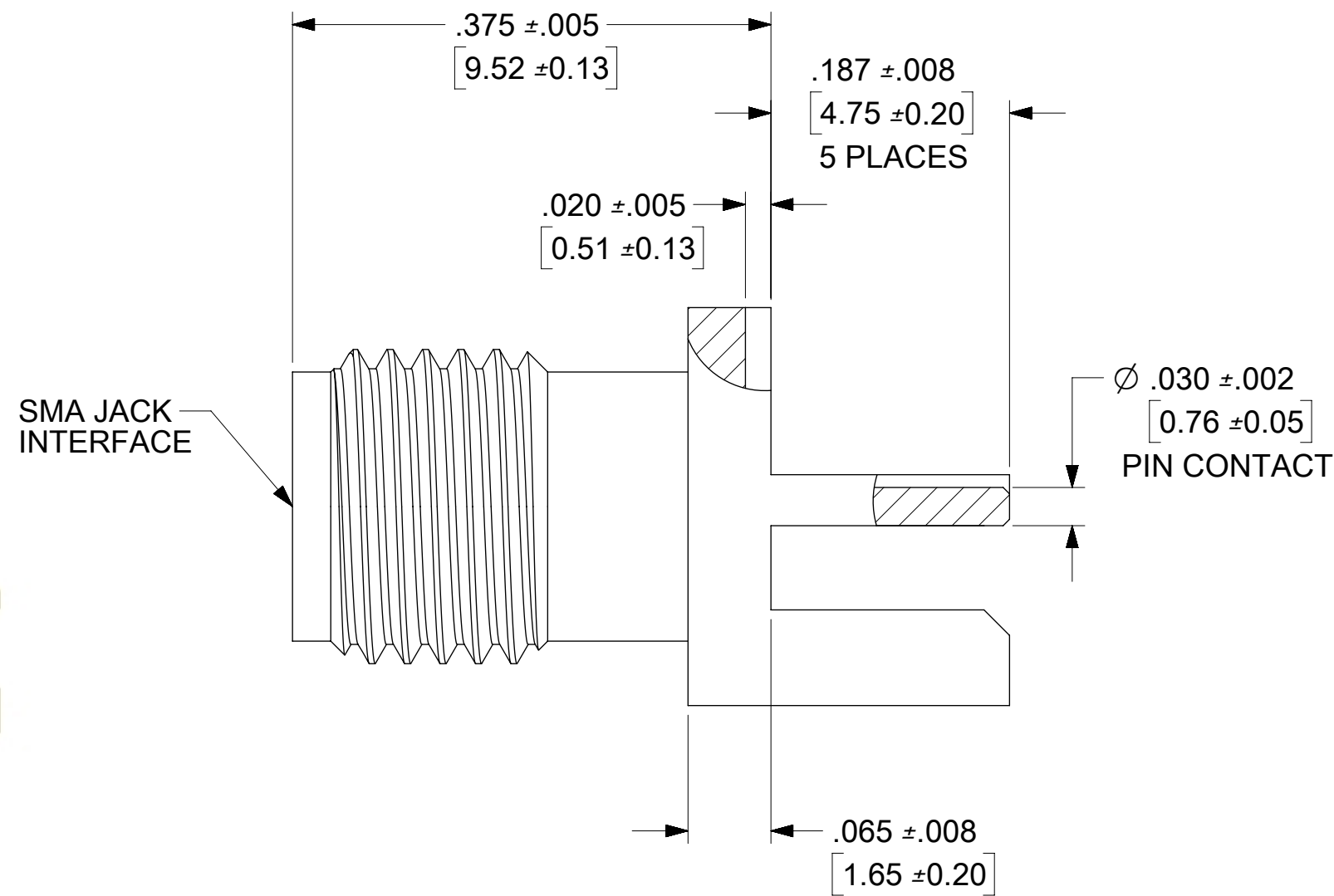
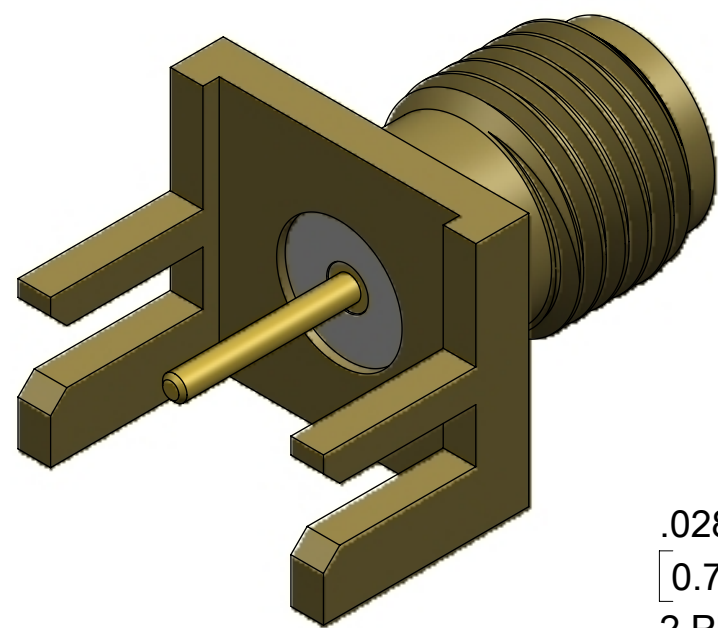
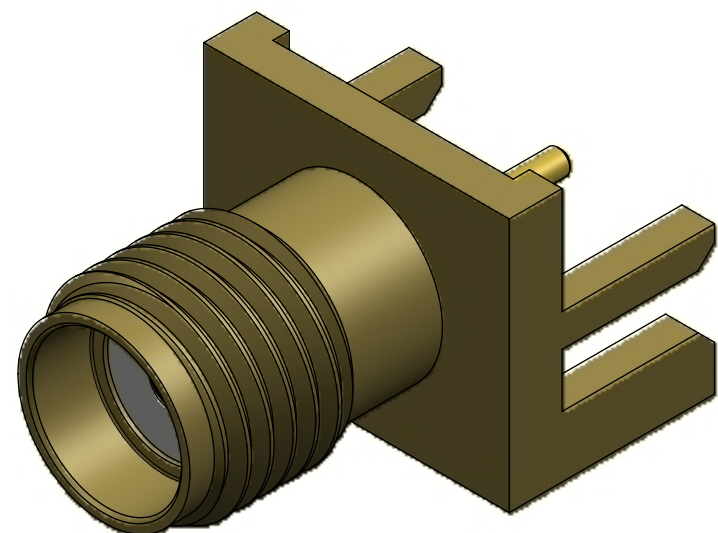


MATERIALS AND FINISHES

**BODY: BRASS
PLATED GOLD (SEE TABLE)**

**CENTER CONTACT: BERYLLIUM COPPER
PLATED GOLD (SEE TABLE)**

INSULATOR: PTFE



PCB PAD (FOR REFERENCE ONLY)

BOARD THICKNESS: .062 [1.57]
BOARD MATERIAL: FR4 WITH 1.0 OZ (28 g) COPPER ON BOTTOM (GROUND) SIDE

73251-1153	GOLD (1µ-in MIN) OVER NICKEL (50µ-in MIN)	GOLD (5µ-in MIN) OVER NICKEL (50µ-in MIN)	TRAY (80 PIECES)
73251-1152	GOLD (10µ-in MIN) OVER NICKEL (50µ-in MIN)	GOLD (10µ-in MIN) OVER NICKEL (100µ-in MIN)	TRAY (20 PIECES)
73251-1151	GOLD (10µ-in MIN) OVER NICKEL (50µ-in MIN)	GOLD (10µ-in MIN) OVER NICKEL (100µ-in MIN)	ONE 73251-1150 PER BAG
73251-1150	GOLD (10µ-in MIN) OVER NICKEL (50µ-in MIN)	GOLD (10µ-in MIN) OVER NICKEL (100µ-in MIN)	TRAY (80 PIECES)

PART NO.	BODY	CONTACT	DESCRIPTION
	PLATING		PACKAGING

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SYMBOLS	DIMENSION UNITS	SCALE	CURRENT REV DESC: SEE ECM
▽ = 0	INCH	NTS	
▽ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		
▽ = 0		MM	INCH
▽ = 0	4 PLACES ±	±	
▽ = 0	3 PLACES ±	± 0.005	
▽ = 0	2 PLACES ±	± 0.01	
▽ = 0	1 PLACE ±	± 0.25	
▽ = 0	0 PLACES ±	±	
▽ = 0	ANGULAR TOL	± 2.0°	
▽ = 0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

EC NO: 172847	DRWN: LMEIER	2018/02/23
CHK'D: SSSHAH	2018/03/01	
APPR: AROBERTSON	2018/03/01	
INITIAL REVISION:	DRWN: TEF	2002/06/27
	APPR: GMH	2002/06/27

THIRD ANGLE PROJECTION		DRAWING	SERIES
		C-SIZE	73251

DOCUMENT NUMBER		DOC TYPE	DOC PART	REVISION
SD-73251-115		PSD	001	B1

MATERIAL NUMBER		CUSTOMER	SHEET NUMBER
SEE TABLE			1 OF 1

PS-89675-3460	PRODUCT SPECIFICATION
MIL-STD-348B, FIG. 310-2	INTERFACE
SPECIFICATION	DESCRIPTION
DOCUMENT STATUS	P1
RELEASE DATE	2018/03/01 20:38:20